



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<p><b>TO:</b></p> <p><b>Part No.:</b></p> <p><b>Customer's Part No.:</b></p>	<p>Please return this copy as a certification of your approval</p> <p><b>Checked &amp; Approved by:</b></p> <p><b>Date:</b></p>

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Part No.	:	SF0608
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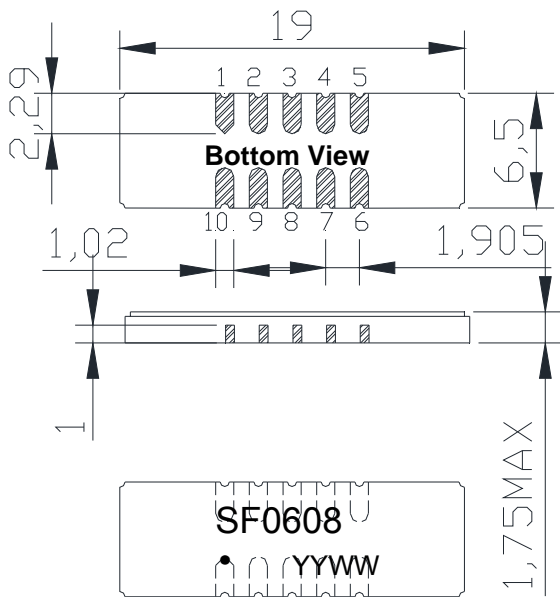
**Application**

- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Passband 2.2 MHz

**Features**

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 19.00x6.50x1.75mm<sup>3</sup>
- Package Code SMD19
  
- **Electrostatic Sensitive Device(ESD)**

**Package Dimensions (Unit: mm)**



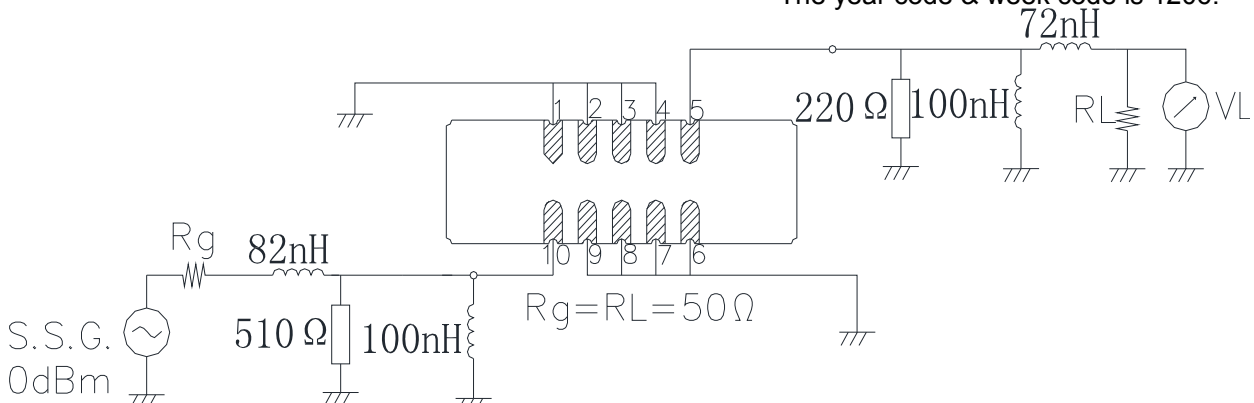
**Pin Configuration**

Pin No.	Description
10	Input
5	Output
1,2,3,4,6,7,8,9	Ground

**Marking Description**

<b>S</b>	Trademark
<b>F</b>	SAW Filter
<b>0608</b>	Part Number
●	Pin 1
YYWW	Year Code & Week Code

**Test Circuit(Bottom View)**



\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

**Performance****Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

**Electronic Characteristics**

Test Temperature: 25°C ± 2°C

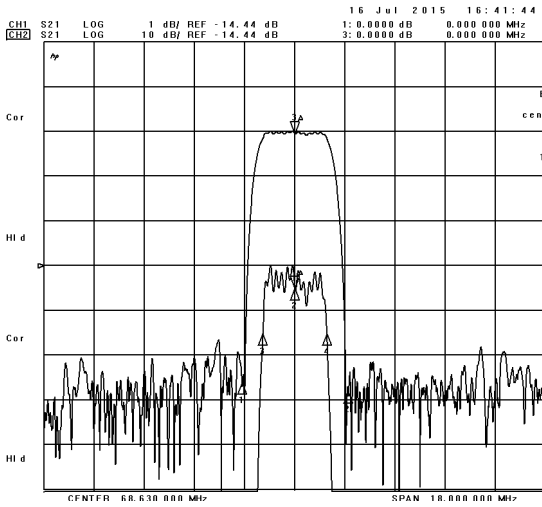
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

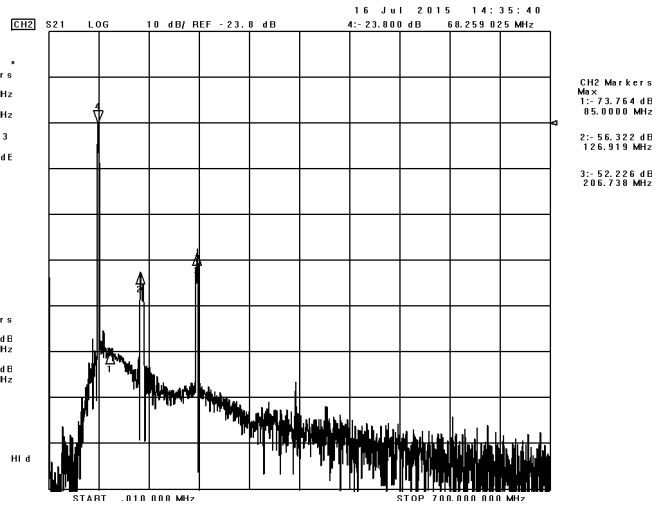
Item		Minimum	Typical	Maximum	Unit
Center Frequency	f <sub>c</sub>		68.63		MHz
Insertion Loss(Fc)	IL		14.9	16.0	dB
1 dB Bandwidth(Relative to Fc)	BW <sub>1dB</sub>	2.20	2.30	2.40	MHz
Absolute Attenuation(With a base of Fc)	α				
	66.73MHz	46.5	55.0		dB
	70.53MHz	46.5	57.0		dB
	58.63-66.73MHz	45.0	46.0		dB
	70.53-78.63MHz	45.0	48.0		dB
	85.00-700.00MHz	25.0	28.0		
Phase Linearity	67.53-69.73MHz		8.0	10.0	deg
Input VSWR	68.63MHz		1.71:1	2.50:1	/
Output VSWR	68.63MHz		1.41:1	2.00:1	/

Frequency Characteristics

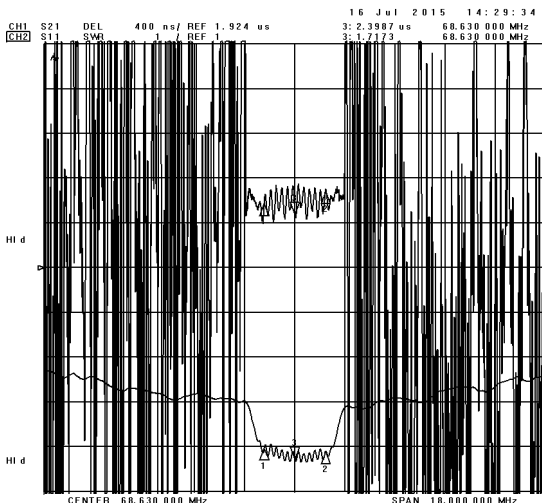
Frequency Response



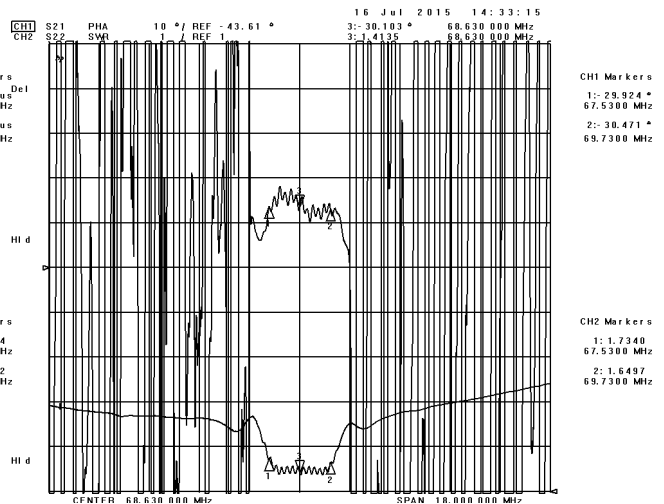
Frequency Response (wideband)



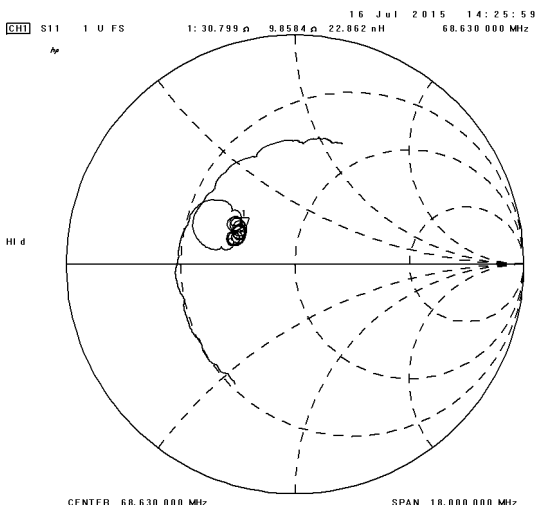
Delay Ripple & S11 VSWR



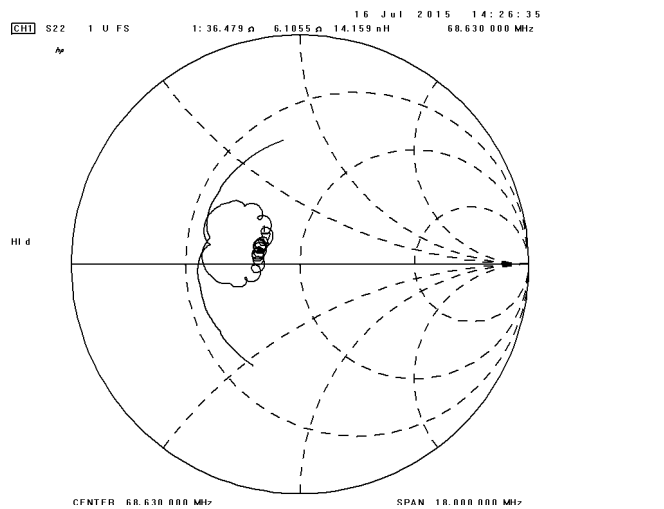
Phase Linearity & S22 VSWR



S11 Smith Chart

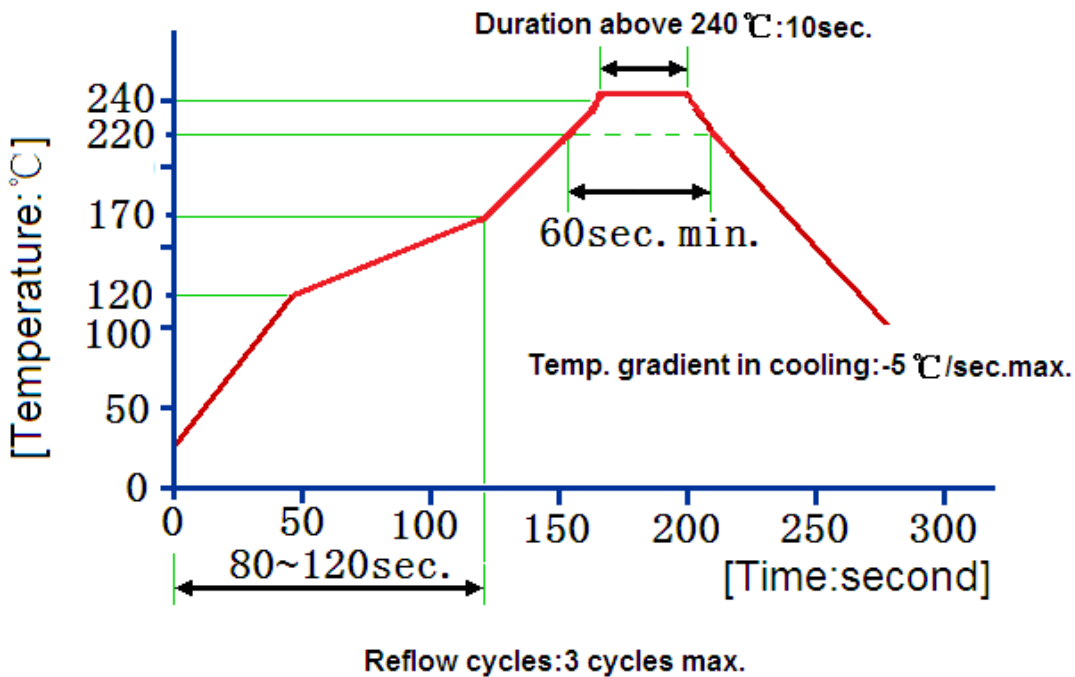


S22 Smith Chart



**Reliability (The SAW components shall remain electrical performance after tests)**

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: $85^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , Duration: 250h , Recovery time: $2\text{h}\pm 0.5\text{h}$ (2) Temperature: $-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$ , Duration: 250h ,Recovery time: $2\text{h}\pm 0.5\text{h}$
2	Humidity Test	Conditions: $60^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , 90~95% RH                          Duration: 250h
3	Thermal Shock	Heat cycle conditions: $\text{TA}=-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$ , $\text{TB}=85^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , $t_1=t_2=30\text{min}$ , Switch time: $\leq 3\text{min}$ , Cycle time: 100 times, Recovery time: $2\text{h}\pm 0.5\text{h}$ .
4	Vibration Fatigue	Frequency of vibration: 10~55Hz                          Amplitude: 1.5mm Directions: X,Y and Z    Duration: 2h
5	Drop Test	Cycle time: 10 times    Height: 1.0m
6	Solder Ability Test	Temperature: $245^{\circ}\text{C}\pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB: 1mm , Solder condition: $260^{\circ}\text{C}\pm 5^{\circ}\text{C}$ , Duration: $10\pm 1\text{s}$ (2)Temperature of Soldering Iron: $350^{\circ}\text{C}\pm 10^{\circ}\text{C}$ , Duration: 3~4s , Recovery time : $2 \pm 0.5\text{h}$

**Recommended Reflow Soldering Diagram**

**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.